SDAS204A - APRIL 1982 - REVISED DECEMBER 1994

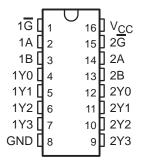
- Designed Specifically for High-Speed Memory Decoders and Data Transmission Systems
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

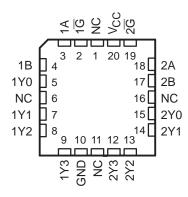
The 'ALS139 are dual 2-line to 4-line decoders/demultiplexers designed for use in high-performance memory-decoding or datarouting applications requiring very short propagation delay times. In high-performance memory systems, these devices can minimize the effects of system decoding. When employed with high-speed memories utilizing a fast-enable circuit, the delay times of these decoders and the enable time of the memory are usually less than the typical access time of the memory. Therefore, the effective system delay introduced by the Schottky-clamped system decoder is negligible.

The 'ALS139 comprise two individual 2-line to 4-line decoders in a single package. The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. These

SN54ALS139...J PACKAGE SN74ALS139...D OR N PACKAGE (TOP VIEW)



SN54ALS139 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

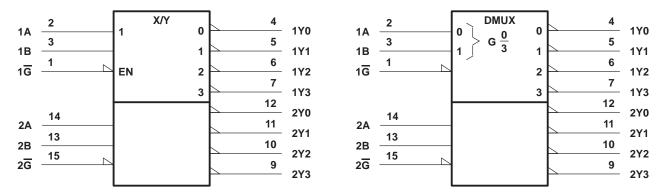
decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit. All inputs are clamped with high-performance Schottky diodes to suppress line ringing and simplify system design.

The SN54ALS139 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS139 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

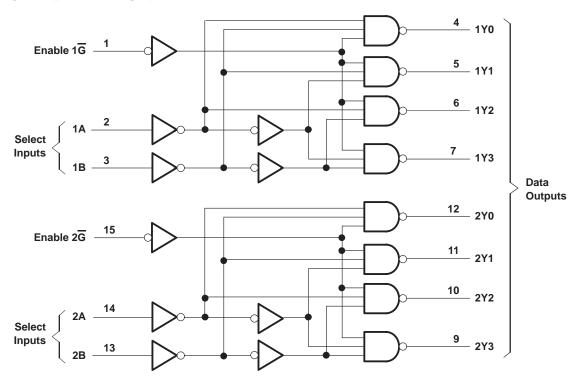
IN	IPUTS			OUT	PUTS	
ENABLE	SEL	ECT		0011	-013	
G	В	Α	Y0	Y1	Y2	Y3
Н	Х	Х	Н	Н	Н	Н
L	L	L	L	Н	Н	Н
L	L	Н	Н	L	Н	Н
L	Н	L	Н	Н	L	Н
L	Н	Н	Н	Н	Н	L

logic symbols (alternatives)†



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54ALS139	-55°C to 125°C
SN74ALS139	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN54ALS139			SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-0.4			-0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	SN	54ALS1	39	SN74ALS139			UNIT	
PARAWETER	TEST CON	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNII	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_1 = -18 \text{ mA}$			-1.2			-1.2	V
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
Voi	V _{CC} = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VoL	VCC = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lін	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _Ι L	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IO§	$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc	V _{CC} = 5.5 V	-		8	13		8	13	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L	= 50 pl = 500 £			UNIT
	, ,	, ,	SN54A	LS139	SN74ALS139		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V	3	17	3	14	nc
^t PHL	AUID	T	3	17	3	14	ns
^t PLH	G	V	3	17	3	14	ns
^t PHL	9	1	3	18	3	15	115

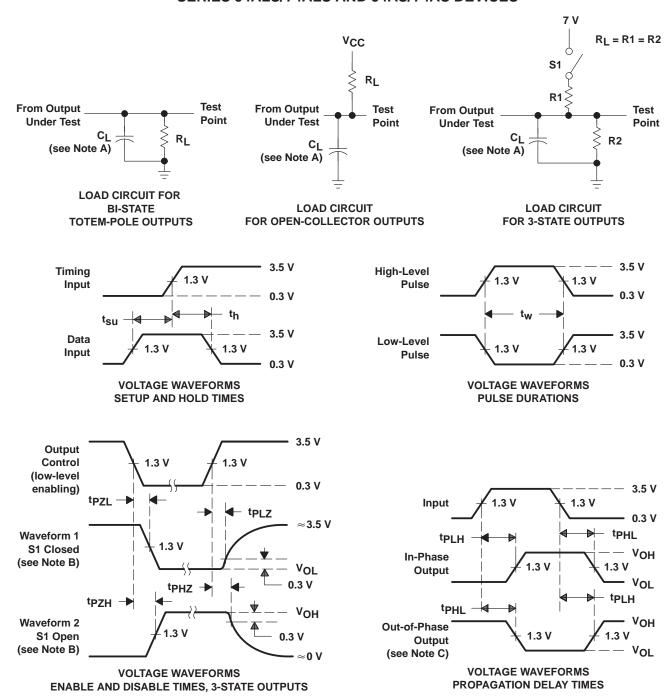
 $[\]P$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-87683012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87683012A SNJ54ALS 139FK
5962-8768301EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8768301EA SNJ54ALS139J
SN74ALS139D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	ALS139
SN74ALS139DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS139
SN74ALS139DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS139
SN74ALS139N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS139N
SN74ALS139N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS139N
SN74ALS139NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS139
SN74ALS139NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS139
SNJ54ALS139FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87683012A SNJ54ALS 139FK
SNJ54ALS139FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 87683012A SNJ54ALS 139FK
SNJ54ALS139J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8768301EA SNJ54ALS139J
SNJ54ALS139J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8768301EA SNJ54ALS139J

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

PACKAGE OPTION ADDENDUM

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(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS139, SN74ALS139:

Catalog: SN74ALS139

Military: SN54ALS139

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS139DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS139NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS139DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74ALS139NSR	SOP	NS	16	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-87683012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74ALS139N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS139N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS139N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS139N.A	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54ALS139FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS139FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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